

- simultaneously with first step or after the latter, a second step for cutting out the microcomponents in the substrate.

15. A method according to Claim 14, wherein the first mechanical machining step comprises at least two substeps: a first substep for blank-forming and a second substep for finishing.

16. A method according to Claim 14, wherein the first step further comprises a step for (obtaining optical quality) for the microrelief.

17. A method according to Claim 14, wherein the microrelief is made with a single tool (68, 78) moved at the surface of the substrate.

18. A method according to Claim 14, wherein the microrelief is made by several tools (88, 98) working (simultaneously and/or in succession).

19. A method according to Claim 14, wherein the microrelief is made with a saw moved along one direction at a time.

20. A method according to Claim 14, wherein the microcomponents are micropisms (80, 100).